

AMENDMENTS TO THE CLAIMS:

This listing of the claims is a complete listing of the claims as they currently stand.

1. (amended) A printed wiring assembly, comprising:

a printed circuit board, having on a major surface thereof a plurality of I/O pads situated within an integrated circuit package receiving region, and having thereon at least one solder deposit that is not a part of the plurality of I/O pads;

a surface mount integrated circuit package soldered to the I/O pads at the receiving region; and

a film adhesive situated on the printed circuit board and covering the solder deposit and a portion of the major surface, adhesively bonding the surface mount integrated circuit package to the printed circuit board, wherein the film adhesive does not extend completely around the package perimeter.
2. (original) The printed wiring assembly as described in claim 1, wherein the film adhesive is 'L-shaped'.
3. (original) The printed wiring assembly as described in claim 1, wherein the film adhesive is an open mesh grid.
4. (canceled)
5. (original) The printed wiring assembly as described in claim 1, wherein a portion of the film adhesive extends beyond a perimeter of the package.
6. (original) The printed wiring assembly as described in claim 1, wherein the film adhesive does not contact the plurality of I/O pads.
7. (original) The printed wiring assembly as described in claim 1, wherein the film adhesive contains one or more additives selected from the group consisting of an inorganic filler, a dye, a pigment, and a stiffening layer.
8. (original) The printed wiring assembly as described in claim 1, wherein the film adhesive is a thermoset adhesive.
9. (original) The printed wiring assembly as described in claim 1, wherein the film adhesive is a thermoplastic adhesive.
10. (original) The printed wiring assembly as described in claim 1, wherein the film adhesive is softened by electromagnetic energy.

11.(currently amended) ~~The printed wiring assembly as described in claim~~

~~4,~~ A printed wiring assembly, comprising:

a printed circuit board, having on a major surface thereof a plurality of I/O pads situated within an integrated circuit package receiving region, and having thereon at least one solder deposit that is not a part of the plurality of I/O pads;

a surface mount integrated circuit package soldered to the I/O pads at the receiving region; and

a film adhesive situated on the printed circuit board and covering the solder deposit and a portion of the major surface, adhesively bonding the surface mount integrated circuit package to the printed circuit board, wherein the film adhesive is applied as a free film to the printed circuit board major surface prior to soldering the surface mount integrated circuit package to the I/O pads.

12.(amended) A printed wiring assembly, comprising:

a printed circuit board, having on a major surface thereof a plurality of I/O pads situated within an integrated circuit package receiving region, and having thereon at least one solder deposit that is not a part of the plurality of I/O pads;

a surface mount integrated circuit package soldered to the I/O pads at the receiving region;

a film adhesive situated on the printed circuit board and covering the solder deposit and a portion of the major surface, adhesively bonding the integrated circuit package to the printed circuit board;

wherein the film adhesive is applied as a free film to the printed circuit board major surface prior to soldering the surface mount integrated circuit package to the I/O pads;

wherein the film adhesive does not extend completely around the package perimeter; and

wherein the film adhesive does not contact the plurality of I/O pads.

13.(amended) A printed wiring assembly, comprising:

a printed circuit board, having on a major surface thereof an array of solderable pads situated within an integrated circuit package receiving region, and having thereon one or more tack pads distinct from the array of solderable pads;

solder deposited on the array of solderable pads and on the one or more tack pads;

a film adhesive situated on the printed circuit board, covering at least a portion of the solder on the one or more tack pads and covering a portion of the major surface, wherein the film adhesive does not extend completely around the package perimeter; and

a surface mount integrated circuit package soldered to the array of solderable pads and adhesively bonded to the printed circuit board by the film adhesive.

14.(original) The printed wiring assembly as described in claim 13, wherein the one or more tack pads are metal.

15.(original) The printed wiring assembly as described in claim 13, wherein the one or more tack pads are non-metallic.